

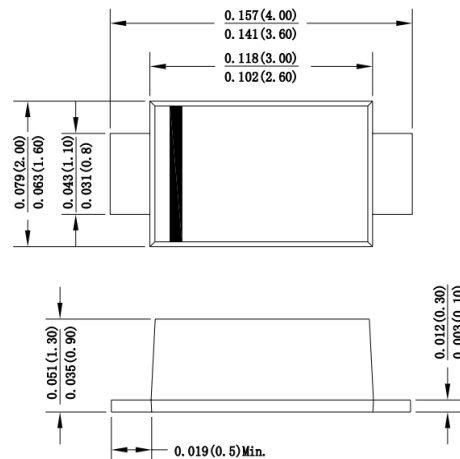
Features

The plastic package carries Underwriters Laboratory
 Flammability Classification 94V-0
 For surface mounted applications
 Built-in strain relief, ideal for automated placement
 Low reverse leakage
 High forward surge current capability
 High temperature soldering guaranteed
 250°C/10 seconds at terminals

Mechanical Data

Case : Molded plastic body
Terminals : Solder plated, solderable per MIL-STD-750, Method 2026
Polarity : Polarity symbol marking on body
Mounting Position : Any
Weight : 0.0007 ounce, 0.02 grams

SOD123FL



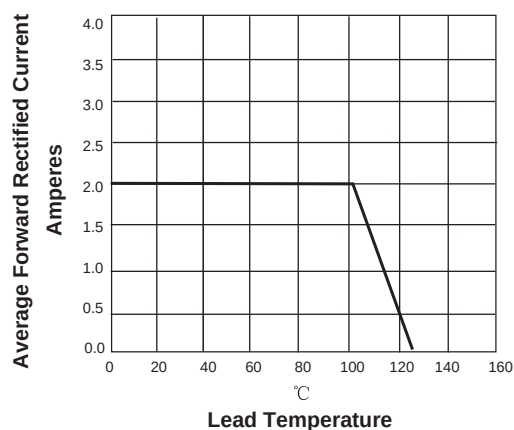
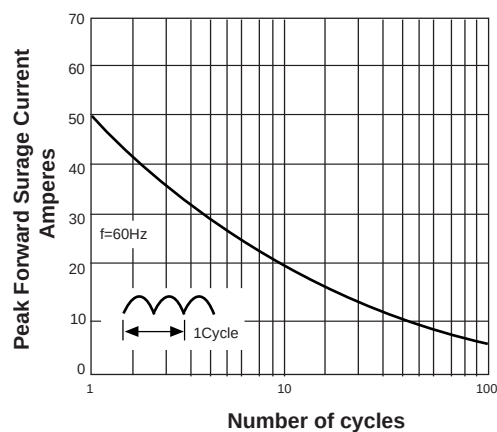
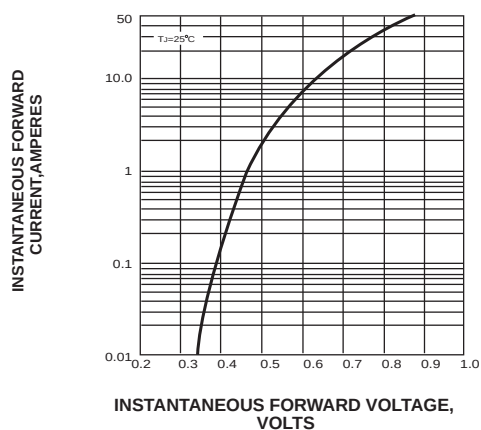
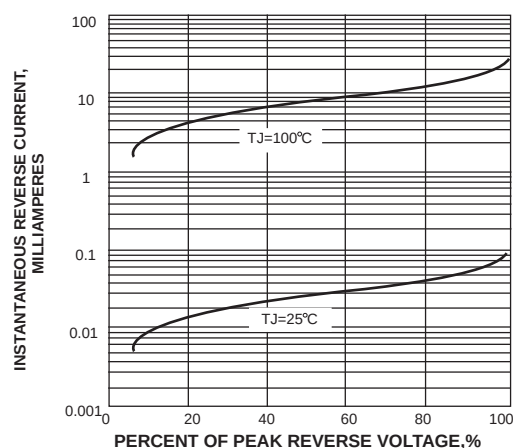
Dimensions in inches and (millimeters)

Maximum Ratings And Electrical Characteristics

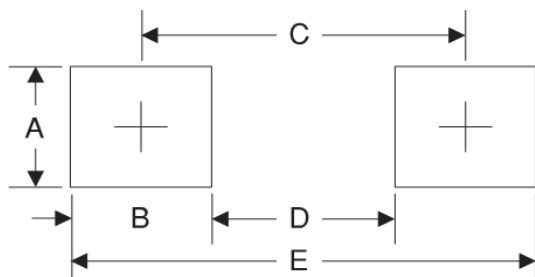
Ratings at 25°C ambient temperature unless otherwise specified. Single phase half-wave 60Hz, resistive or inductive load, for capacitive load current derate by 20%.

Parameter	SYMBOLS	K26L	UNITS
Maximum repetitive peak reverse voltage	V_{RRM}	60	V
Maximum RMS voltage	V_{RMS}	42	V
Maximum DC blocking voltage	V_{DC}	60	V
Maximum average forward rectified current at $T_L=100^\circ\text{C}$	$I_{(AV)}$	2.0	A
Peak forward surge current, 8.3ms single half sine-wave superimposed on rated load	I_{FSM}	50.0	A
Maximum instantaneous forward voltage at 2.0A	V_F	0.55	V
Maximum DC reverse current $T_A=25^\circ\text{C}$ at rated DC blocking voltage $T_A=125^\circ\text{C}$	I_R	0.5 50	mA
Typical thermal resistance	R_{qJA}	85.0	$^\circ\text{C/W}$
Operating junction temperature range	T_J	-55 to +125	$^\circ\text{C}$
Storage temperature range	T_{STG}	-55 to +150	$^\circ\text{C}$

Ratings And Characteristic Curves

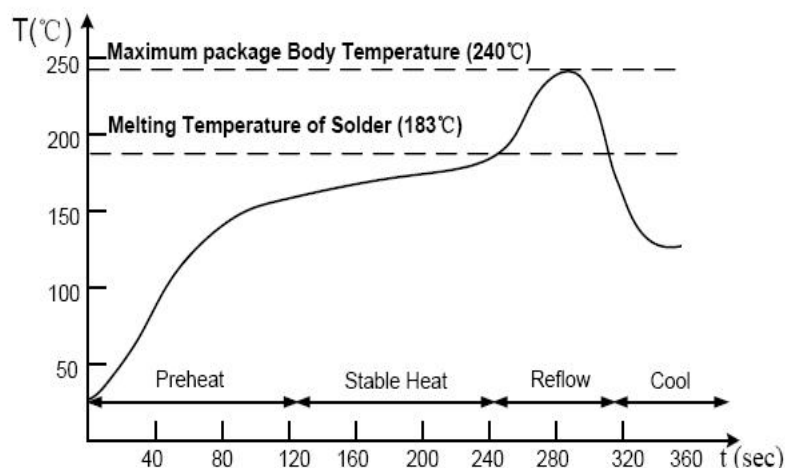
FIG. 1- DERATING CURVE OUTPUT RECTIFIED CURRENT

FIG. 2-MAXIMUM NON-REPETITIVE PEAK FORWARD SURGE CURRENT PER LEG

FIG. 3-TYPICAL FORWARD VOLTAGE CHARACTERISTICS

FIG. 4-TYPICAL REVERSE LEAKAGE CHARACTERISTICS


Suggested Pad Layout



Symbol	Unit (mm)	Unit (inch)
A	1.2	0.048
B	1.15	0.045
C	3.10	0.122
D	1.95	0.077
E	4.25	0.167

Suggested Soldering Temperature Profile

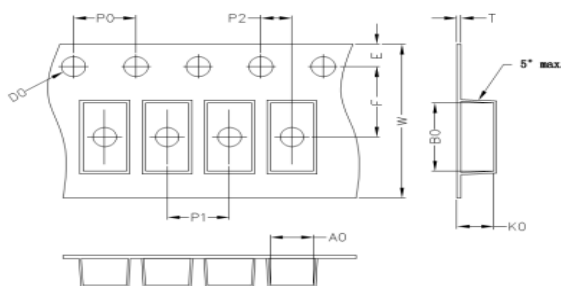


Note

Recommended reflow methods: IR, vapor phase oven, hot air oven, wave solder.
 The device can be exposed to a maximum temperature of 265°C for 10 seconds.
 Devices can be cleaned using standard industry methods and solvents.
 If reflow temperatures exceed the recommended profile, devices may not meet the performance requirements.

Package Information

Carrier Dimension(mm)



A0	B0	K0	D0	E	F
2.15	3.95	1.35	1.55	1.75	3.50
P0	P1	P2	T	W	Tolerance
4.0	4.0	2.0	0.25	8	0.1

Package Specifications

Package	Reel Size	Reel DIA. (mm)	Q'TY/Reel (Kpcs)	Box Size (mm)	QTY/Box (Kpcs)	Carton Size (mm)	Q'TY/Carton (Kpcs)
SOD123FL	7'	178	3	180	15	380*200*200	150

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